

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Hidetoshi Kusano</td><td>07/02/2007</td></tr><tr><td>Kazuaki Yazawa</td><td>06/26/2007</td></tr></tbody></table>	Name	Execution Date	Hidetoshi Kusano	07/02/2007	Kazuaki Yazawa	06/26/2007					
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<table border="1"><tr><td>Name:</td><td>Sony Corporation</td></tr><tr><td>Street Address:</td><td>1-7-1, Konan, Minato-ku</td></tr><tr><td>City:</td><td>Tokyo</td></tr><tr><td>State/Country:</td><td>JAPAN</td></tr><tr><td>Postal Code:</td><td>108-0075</td></tr></table>	Name:	Sony Corporation	Street Address:	1-7-1, Konan, Minato-ku	City:	Tokyo	State/Country:	JAPAN	Postal Code:	108-0075	
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<table border="1"><tr><td>Name:</td><td>Sony Computer Entertainment Inc.</td></tr><tr><td>Street Address:</td><td>2-6-21, Minami-Aoyama, Minato-ku</td></tr><tr><td>City:</td><td>Tokyo</td></tr><tr><td>State/Country:</td><td>JAPAN</td></tr><tr><td>Postal Code:</td><td>107-0062</td></tr></table>	Name:	Sony Computer Entertainment Inc.	Street Address:	2-6-21, Minami-Aoyama, Minato-ku	City:	Tokyo	State/Country:	JAPAN	Postal Code:	107-0062	
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PROPERTY NUMBERS Total: 1											
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Application Number:	11751694										
CORRESPONDENCE DATA											
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CH \$40.00 11751694

ATTORNEY DOCKET NUMBER:	SCEP 23.056
NAME OF SUBMITTER:	Jeney Han
Total Attachments: 2 source=SCEP 23.056 - Assignment#page1.tif source=SCEP 23.056 - Assignment#page2.tif	

ASSIGNMENT

Docket No. SCEP 23.056

WHEREAS, the below named inventor, ASSIGNOR, has made a certain new and useful invention in:
SEMICONDUCTOR DEVICE HAVING HIGH COOLING EFFICIENCY AND METHOD FOR MANUFACTURING THE
SAME

for which

(check one)

☐ an application is being filed concurrently herewith,

☒ an application for a Patent of the United States was filed on May 22, 2007
and given Application Serial No. 11/751,694

and WHEREAS, SONY CORPORATION having a place of business at _____
1-7-1, Konan, Minato-ku, Tokyo 108-0075 Japan and Sony Computer Entertainment, Inc.
having a place of business at 2-6-21, Minami-Aoyama, Minato-ku, Tokyo 107-0062 Japan,
ASSIGNEE is desirous of obtaining the entire right, title and interest in, to and under the said invention and the said application.

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to me in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, the said ASSIGNOR has sold, assigned, transferred and set over, and by these presents does hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title and interest in, to and under the said invention, and the said United States application and all divisions, renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may hereafter be filed for said invention in any country or countries foreign to the United States, together with the right to file such applications and the right to claim for the same the priority rights derived from said United States application under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application is filed, as may be applicable; and all forms of industrial property protection, including, without limitation, patents, utility models, inventor's certificates and designs which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof;

ASSIGNOR authorizes and requests the Commissioner of Patents and Trademarks of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents or other evidence or forms of industrial property protection on applications as aforesaid, to issue the same to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument; and

ASSIGNOR covenants and agrees that he has full right to convey the entire interest herein assigned, and has not executed, and will not execute, any agreement in conflict herewith; and

ASSIGNOR further covenants and agrees that he will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and foreign applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention in all countries.

Full name of sole or first inventor Hidetoshi KUSANO
Inventor's Signature Hidetoshi Kusano Date July 2, 2007
Residence Dita, Japan Citizenship Japanese
Post Office Address c/o SONY CORPORATION
1-7-1, Konan, Minato-ku, Tokyo 108-0075 Japan

Full name of second joint inventor, if any Kazuaki YAZAWA
Second Inventor's Signature _____ Date _____
Residence _____, Japan Citizenship Japanese
Post Office Address c/o Sony Computer Entertainment Inc.
2-6-21, Minami-Aoyama, Minato-ku, Tokyo 107-0062 Japan

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Full name of sole or first inventor Hidetoshi KUSANO
Inventor's Signature _____ Date _____
Residence _____, Japan _____ Citizenship Japanese
Post Office Address c/o SONY CORPORATION
1-7-1, Konan, Minato-ku, Tokyo 108-0075 Japan

Full name of second joint inventor, if any Kazuaki YAZAWA
Second Inventor's Signature 矢澤和明 Date June 26, 2007
Residence Chiba, Japan _____ Citizenship Japanese
Post Office Address c/o Sony Computer Entertainment Inc.
2-6-21, Minami-Aoyama, Minato-ku, Tokyo 107-0062 Japan